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a semiconductor substrate;
at least two semiconductor components provided on the principal surface of the substrate;
electrodes of the at least two components provided on the substrate so as to substantially eliminate the electrical interference between the two semiconductor components;
a first group of through holes, which pass from the principal surface through the backside of the substrate and are provided in respective regions of the substrate under the electrodes;
a first conductor film provided on the side faces of the first group of through holes;
a second group of through holes, which differ from the first group of through holes, which pass from the principal surface through the backside of the substrate between the components;
a second conductor film provided on the side faces of the second group of through holes;
and
a wiring layer, which is provided on the backside of the substrate and is in contact with the first and second conductor films.

Please add new claims 8, 9 and 10 as follows:

-- 8. The device of Claim 1, where in the multiple through holes stand in a line.

9. A semiconductor device comprising:
a semiconductor substrate;
at least two semiconductor components provided on the principal surface of the substrate;
multiple through holes, which pass from the principal surface through the backside of the substrate and are provided in a region of the substrate between at least the two components so as to substantially eliminate the electrical interference between at least the two semiconductor components; and
a conductor film formed on the side faces of the through holes.